



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-01-24
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacobello	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SM6T82CAY	AHZG*TYB082D	A	64BA	2017-01-24
Amount	UoM	Unit type	ST ECOPACK Grade	
98.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	4.2-3.7-2.37	2	J bend	
Comment	SMB CLIP (SOD 6)			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 5th August 2016			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.07	Die / Leadframe	755
Lead	1.45	Soft solder	14745

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	AHZG*TYB082D					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.601	mg	supplier	die	Silicon (Si)	7440-21-3		1.572	mg	981898	16051
				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	3122	51
				supplier	Passivation	Silicon Oxide	7631-86-9		0.006	mg	3745	61
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.006	mg	3745	61
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1248	20
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.010	mg	6242	102
Leadframe	Copper & its alloys	40.745	mg	supplier	alloy	Copper (Cu)	7440-50-8		40.623	mg	997006	414520
				supplier	alloy	Iron (Fe)	7439-89-6		0.041	mg	1006	418
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.012	mg	294	122
				supplier	metallization	Nickel (Ni)	7440-02-0		0.064	mg	1571	653
				supplier	metallization	Phosphorus (P)	12185-10-3		0.005	mg	123	51
				supplier	alloy	Lead (Pb)	7439-92-1	7a-Lead in high mel	1.445	mg	920382	14740
Soft solder	Solder	1.570	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	1.445	mg	920382	14740
				supplier	solder	Silver (Ag)	7440-22-4		0.078	mg	49682	796
				supplier	solder	Tin (Sn)	7440-31-5		0.039	mg	24841	398
				supplier	solder	flux residue	Proprietary		0.008	mg	5095	82
Encapsulation	Other Organic Materials	34.943	mg	supplier	mold compound	Amorphous Silica	7631-86-9		25.543	mg	730990	260643
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		6.639	mg	189995	67741
				supplier	mold compound	Phenol resin	9003-35-4		1.048	mg	29992	10694
				supplier	mold compound	Bisphenol A-bisphenol A diglycidyle ether poly	25036-25-3		1.048	mg	29992	10694
				supplier	mold compound	Carbon black	1333-86-4		0.315	mg	9015	3214
				supplier	mold compound	Triphenylphosphine	603-35-0		0.245	mg	7011	2500
Connections coating	Solder	0.811	mg	supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		0.105	mg	3005	1071
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.811	mg	1000000	8276
Clip	Copper & its alloys	18.330	mg	supplier	alloy	Copper (Cu)	7440-50-8		18.330	mg	1000000	187041